Abstract

Method for polishing the edge of a semiconductor wafer

A method for polishing the edge of a semiconductor wafer, comprising: (a) providing a semiconductor wafer which has been polished on its side surfaces and which has a rounded edge; (b) polishing the edge of the semiconductor wafer by fixing the semiconductor wafer on a centrally rotating chuck, delivering the semiconductor wafer and a centrally rotating polishing drum, which is inclined with respect to the chuck and to which a polishing pad, containing fixedly bonded abrasives, is applied, and pressing semiconductor wafer and polishing drum onto one another while a polishing agent solution containing no solids is continuously supplied.

No Figure.